



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Adrian E. Ong
Title: Bonding Pads for Testing of a Semiconductor Device
Application No.: 10/608,613
Filing Date: June 27, 2003
Examiner: Minh Nhut Tang
Group Art Unit: 2829
Confirmation No.: 2220
Law Office: Sidley Austin Brown & Wood LLP
Mail Stop Issue Fee
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sirs/Madam:

Applicant submits seventeen (17) sheets of formal drawings, consisting of Figures 1A, 1B, 2A, 2B, 2C, 3, 4, 5, 6, 7, 8, 9A1, 9A2, 9A3, 9A4, 9B1, 9B2, 9C1, 9C2, 9D, 9E1, and 9E2, in the above-named application. If there are any questions regarding these drawings, please call the undersigned at (415) 772-7428.

EXPRESS MAIL LABEL NO.:

Respectfully submitted,

EV 611 225 607 US

By:

Philip W. Woo
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March 4, 2005
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